

# CSD95420RCB 同期整流式降圧 NexFET™ スマート・パワー・ステージ

## 1 特長

- 50A のピーク連続電流
- 15A 時に 94% を超えるシステム効率
- 高周波数 (最高 1.75MHz) での動作
- ダイオード・エミュレーション機能
- 温度補償された双方向電流検出
- アナログ温度出力
- フォルト監視
- 3.3V および 5V の PWM 信号と互換
- トライステート PWM 入力
- ブートストラップ・スイッチ内蔵
- 貫通電流保護用に最適化されたデッドタイム
- QFN パッケージ
  - 高密度
  - 4mm × 5mm
  - 非常に低いインダクタンス
  - システム最適化された PCB 占有面積
  - 熱特性強化型ツォーリング
  - RoHS 準拠
  - 鉛フリーの端子メッキ処理
  - ハロゲン不使用

## 2 アプリケーション

- マルチフェーズの同期整流式降圧コンバータ
  - 高周波アプリケーション
  - 大電流、低デューティ・サイクルのアプリケーション
- POL DC/DC コンバータ
- メモリ・カードおよびグラフィック・カード
- デスクトップ PC およびサーバー向け VR13.x / VR14.x V-Core 同期整流式降圧コンバータ

## 3 概要

CSD95420RCB NexFET™ 電力段は、高電力、高密度の同期整流式降圧コンバータ向けに高度に最適化されています。この製品は、ドライバ・デバイスとパワー MOSFET を統合することにより、電力段スイッチングの完結した機能を実現します。この構成により、大電流、高効率、高速のスイッチング能力が、外形 4mm × 5mm の小型パッケージ内で実現されます。このデバイスは、正確な電流および温度検出機能を内蔵することで、システム設計の簡素化と精度の向上を両立しています。PCB 上の占有面積が最適化されているので、設計期間が短縮され、システム全体の設計が簡素化されます。

### 製品情報

デバイス <sup>(1)</sup>	中	数量	パッケージ	出荷形態
CSD95420RCBRCB	13 インチ・リール	2500	QFN 4.00mm × 5.00mm	テープ・アンド・リール

(1) 利用可能なすべてのパッケージについては、データシートの末尾にある注文情報を参照してください。

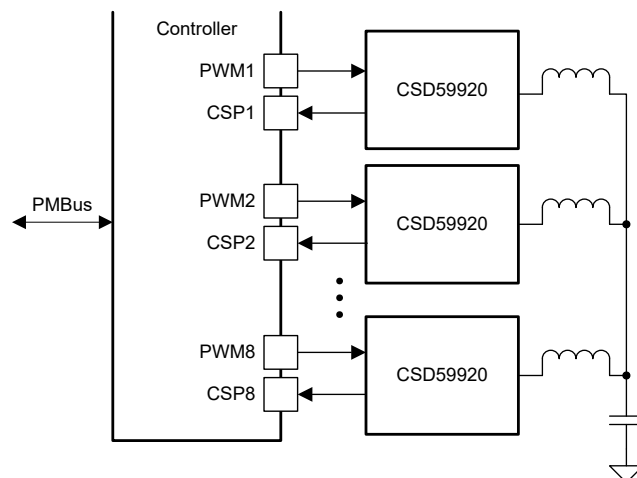


図 3-1. アプリケーション概略



## Table of Contents

<b>1 特長</b> .....	<b>1</b>	5.6 用語集.....	<b>3</b>
<b>2 アプリケーション</b> .....	<b>1</b>	<b>6 Mechanical, Packaging, and Orderable Information</b> ...	<b>3</b>
<b>3 概要</b> .....	<b>1</b>	6.1 Package Option Addendum.....	<b>4</b>
<b>4 Revision History</b> .....	<b>2</b>	6.2 Mechanical Drawing.....	<b>8</b>
<b>5 Device and Documentation Support</b> .....	<b>3</b>	6.3 Recommended PCB Land Pattern.....	<b>9</b>
5.1 Documentation Support.....	<b>3</b>	6.4 Recommended Stencil Opening.....	<b>10</b>
5.2 ドキュメントの更新通知を受け取る方法.....	<b>3</b>	6.5 Alternate Industry Standard Compatible PCB Land Pattern.....	<b>11</b>
5.3 サポート・リソース.....	<b>3</b>	6.6 Alternate Industry Standard Compatible Stencil Opening.....	<b>12</b>
5.4 Trademarks.....	<b>3</b>		
5.5 静電気放電に関する注意事項.....	<b>3</b>		

## 4 Revision History

DATE	REVISION	NOTES
November 2020	*	Initial release.

## 5 Device and Documentation Support

### 5.1 Documentation Support

#### 5.2 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、[ti.com](https://www.ti.com) のデバイス製品フォルダを開いてください。「更新の通知を受け取る」をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取れます。変更の詳細については、修正されたドキュメントに含まれている改訂履歴をご覧ください。

#### 5.3 サポート・リソース

[TI E2E™ サポート・フォーラム](#) は、エンジニアが検証済みの回答と設計に関するヒントをエキスパートから迅速かつ直接得ることができる場所です。既存の回答を検索したり、独自の質問をしたりすることで、設計に必要な支援を迅速に得ることができます。

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ESD による破損は、わずかな性能低下からデバイスの完全な故障まで多岐にわたります。精密な IC の場合、パラメータがわずかに変化するだけで公表されている仕様から外れる可能性があるため、破損が発生しやすくなっています。

#### 5.6 用語集

[テキサス・インスツルメンツ用語集](#) この用語集には、用語や略語の一覧および定義が記載されています。

## 6 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

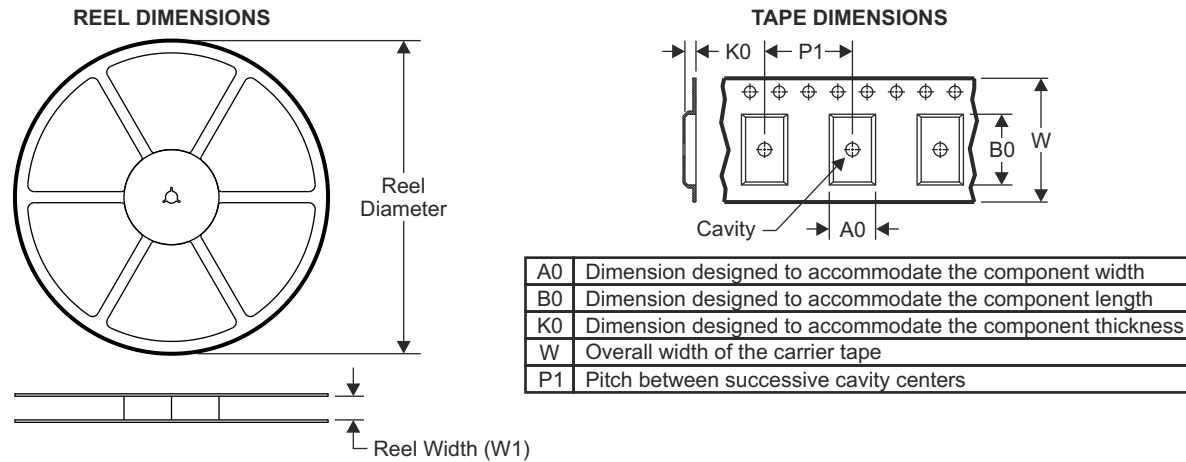
## 6.1 Package Option Addendum

### 6.1.1 Packaging Information

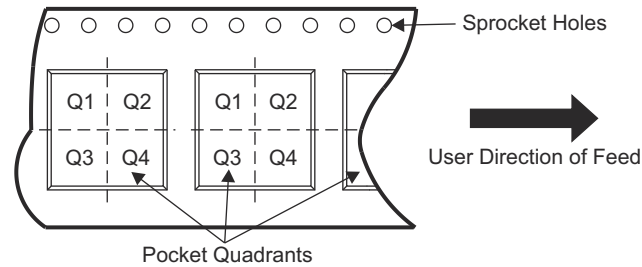
Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>	Op Temp (°C)	Device Marking <sup>(4) (5)</sup>
CSD95420RCBRCB	Active	QFN	RCB	27	2500	PB-Free (RoHS Exempt)	CU NIPDAU	Level-2-260CUNLIM	-55 to 150	59920RB

- (1) The marketing status values are defined as follows:  
**ACTIVE:** Product device recommended for new designs.  
**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.  
**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.  
**PRE\_PROD** Unannounced device, not in production, not available for mass market, nor on the web, samples not available.  
**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.  
**OBSOLETE:** TI has discontinued the production of the device.
- (2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.  
**TBD:** The Pb-Free/Green conversion plan has not been defined.  
**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.  
**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.  
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)
- (3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device
- (5) Multiple Device markings will be inside parentheses. Only on Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.  
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### 6.1.2 Tape and Reel Information



#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



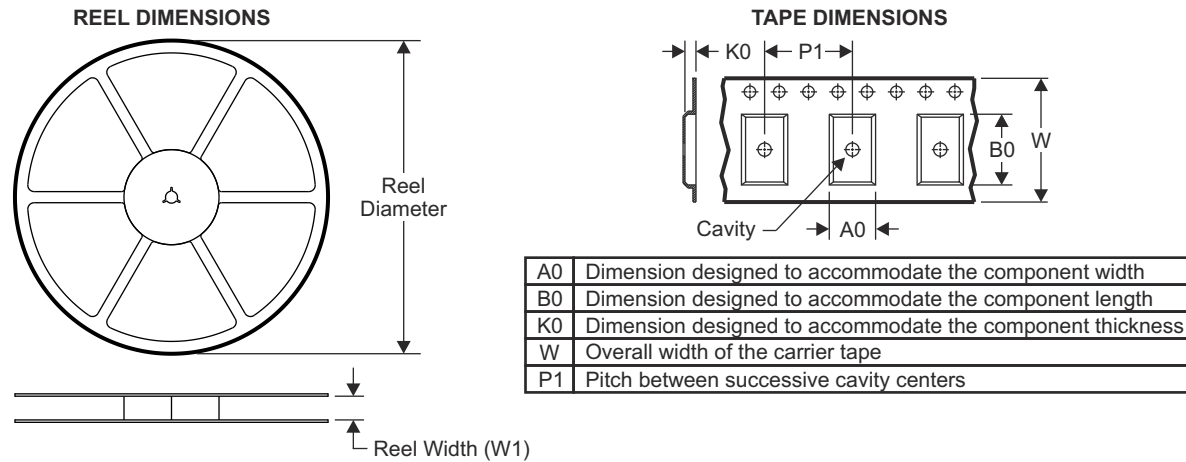
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CSD95420RCB	VQFN-CLIP	RCB	27	2500	330	12.4	4.30	5.30	1.30	8.00	12.00	Q1
CSD95420RCBT	VQFN-CLIP	RCB	27	250	330	12.4	4.30	5.30	1.30	8.00	12.00	Q1

### 6.1.1 Packaging Information

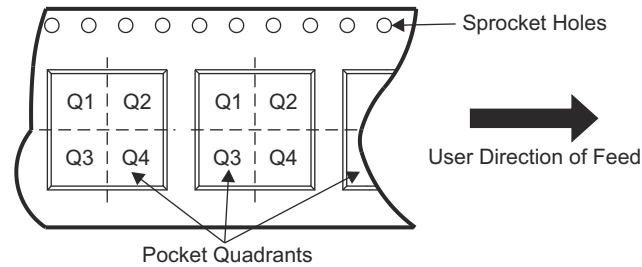
Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>	Op Temp (°C)	Device Marking <sup>(4) (5)</sup>
CSD95420RCBRCB	Active	QFN	RCB	27	2500	PB-Free (RoHS Exempt)	CU NIPDAU	Level-2-260CUNLIM	-55 to 150	59920RB

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- (3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
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### 6.1.2 Tape and Reel Information

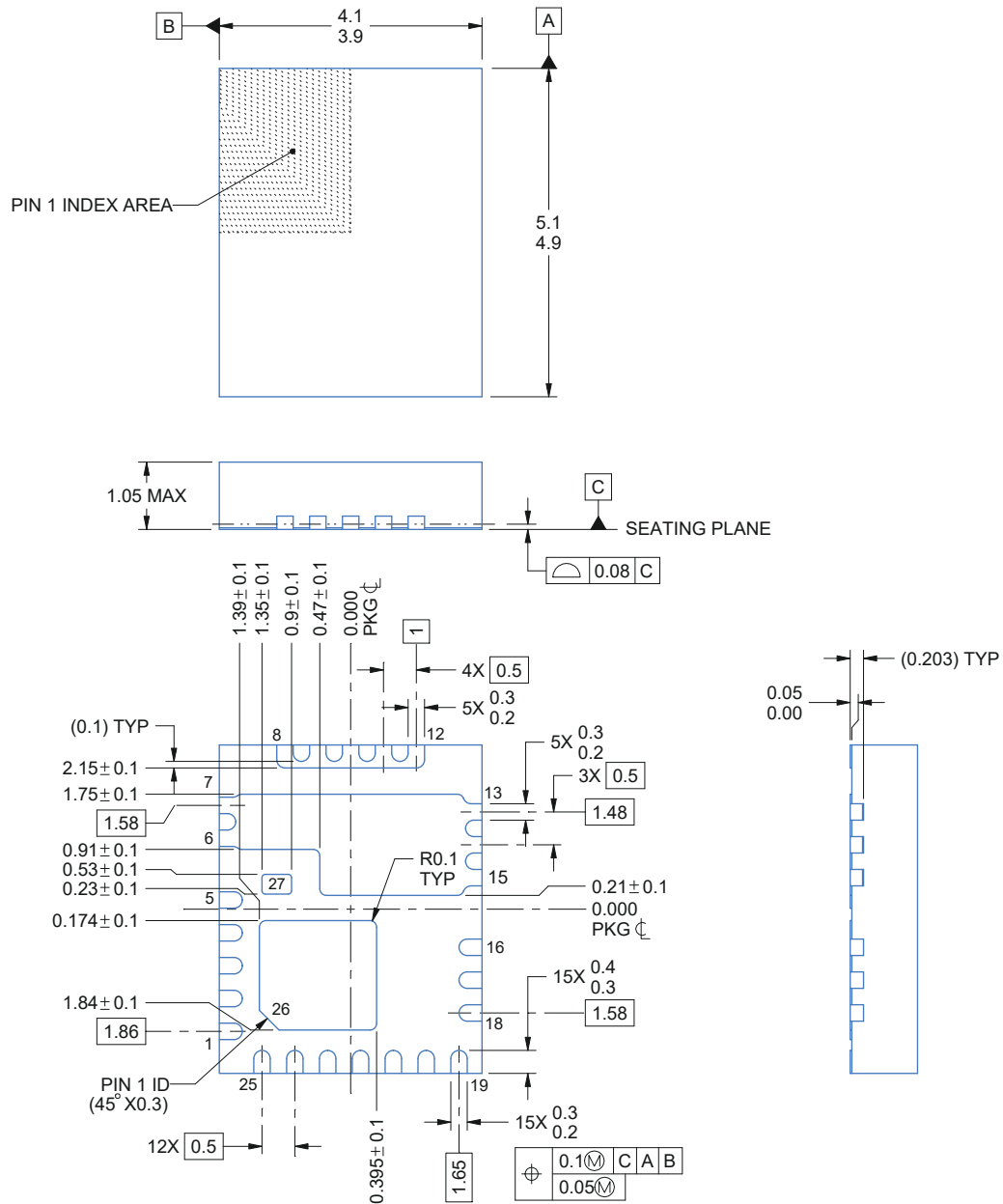


#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CSD95420RCB	VQFN-CLIP	RCB	27	2500	330	12.4	4.30	5.30	1.30	8.00	12.00	Q1
CSD95420RCBT	VQFN-CLIP	RCB	27	250	330	12.4	4.30	5.30	1.30	8.00	12.00	Q1

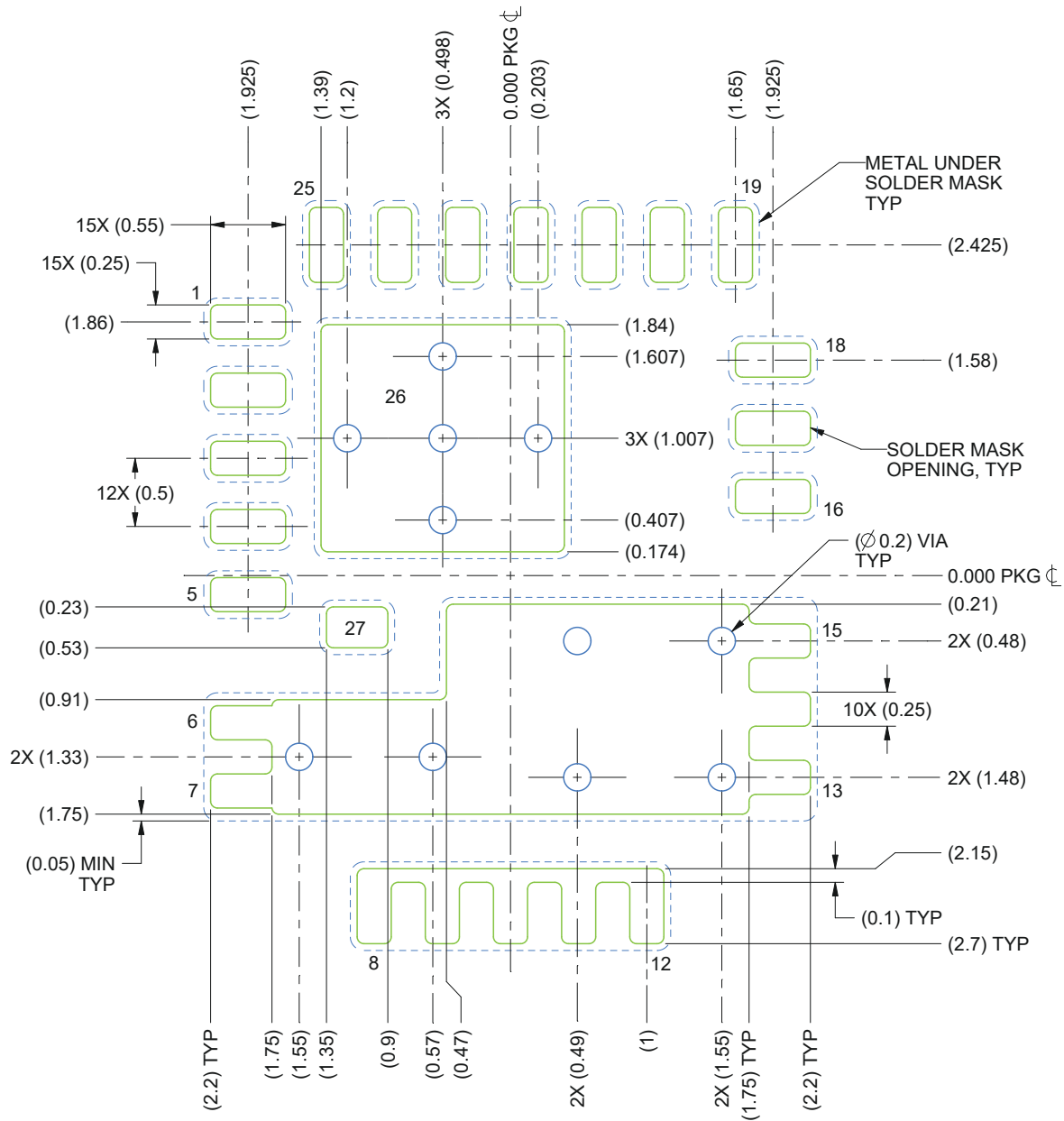
## 6.2 Mechanical Drawing



- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- The package thermal pads must be soldered to the printed circuit board for optimal thermal and mechanical performance.

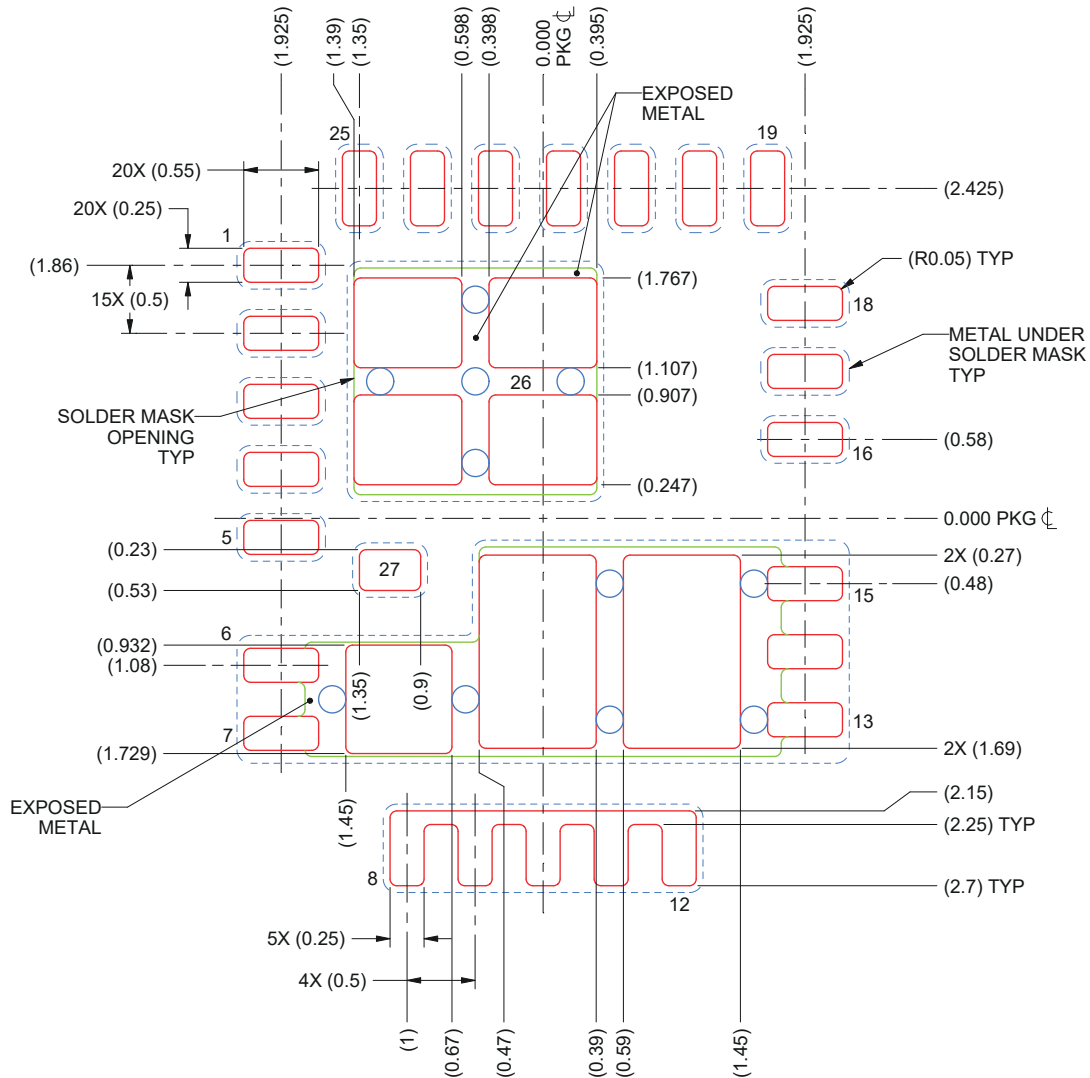


### 6.3 Recommended PCB Land Pattern



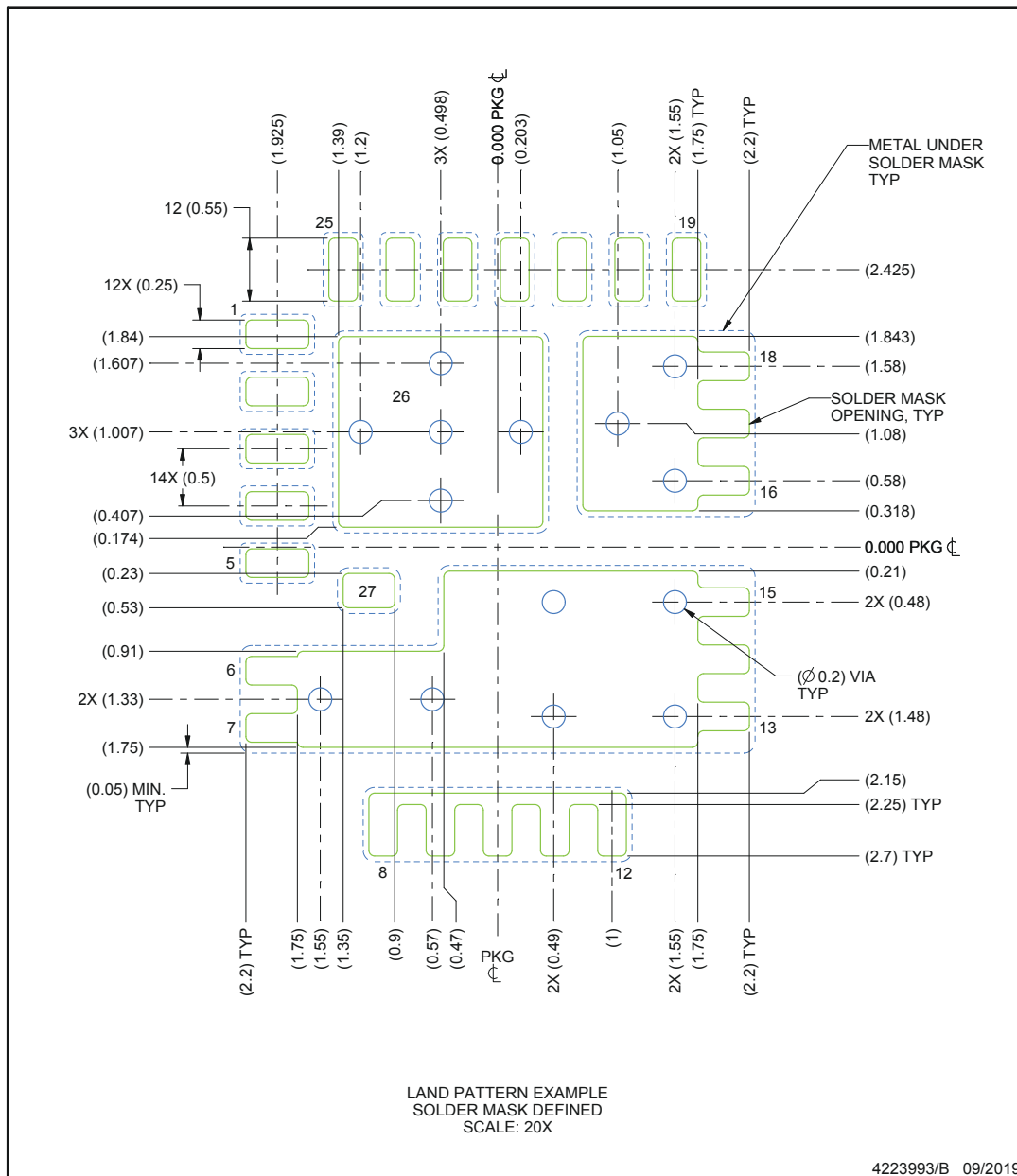
- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This package is designed to be soldered to thermal pads on the board. For more information, see [QFN/SON PCB Attachment \(SLUA271\)](#).

## 6.4 Recommended Stencil Opening



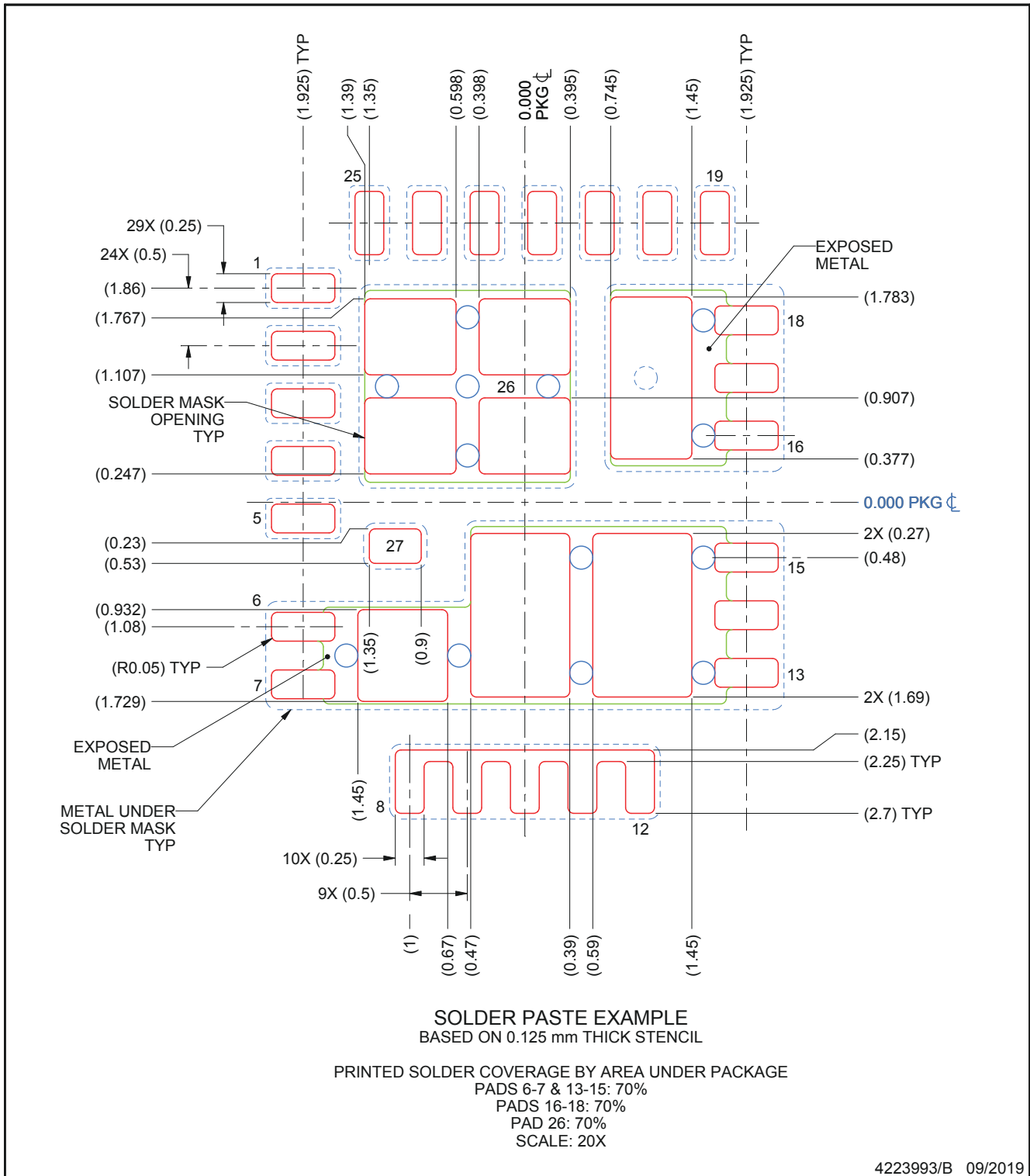
- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

## 6.5 Alternate Industry Standard Compatible PCB Land Pattern



1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pads must be soldered to the printed circuit board for optimal thermal and mechanical performance.
4. This package is designed to be soldered to thermal pads on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).
5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

### 6.6 Alternate Industry Standard Compatible Stencil Opening



**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CSD95420RCB	ACTIVE	VQFN-CLIP	RCB	27	2500	RoHS-Exempt & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	95420RB	<a href="#">Samples</a>
CSD95420RCBT	ACTIVE	VQFN-CLIP	RCB	27	250	RoHS-Exempt & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	95420RB	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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